

LNPTTM THERMOCOMPTM COMPOUND EC006

EC-1006

REGION EUROPE

DESCRIPTION

LNP THERMOCOMP EC006 compound is based on Polyetherimide (PEI) resin containing 30% carbon fiber. Added features of this grade include: Electrically Conductive.

GENERAL INFORMATION

Features	Electrically Conductive, Carbon fiber filled, High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Carbon Fiber
Polymer Types	Polyetherimide (PEI)
Processing Techniques	Injection Molding

INDUSTRY

Automotive
Building and Construction
Consumer
Electrical and Electronics
Industrial

SUB INDUSTRY

Aerospace
Building Component
Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Mobile Phone - Computer - Tablets
Electrical

TYPICAL PROPERTY VALUES

Revision 20230607

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, break, 5 mm/min	219	MPa	ISO 527
Tensile Strain, break, 5 mm/min	1.3	%	ISO 527
Tensile Modulus, 1 mm/min	20200	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	278	MPa	ISO 178
Flexural Modulus, 2 mm/min	15900	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched 80*10*4 +23°C	35	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	6	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
CTE, 23°C to 60°C, flow	7.5E-06	1/°C	ISO 11359-2
CTE, 23°C to 60°C, xflow	3.9E-05	1/°C	ISO 11359-2
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	217	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Density	1.38	g/cm ³	ISO 1183
ELECTRICAL ⁽¹⁾			
Surface Resistivity	1.E+02 – 1.E+04	Ω	ASTM D257
FLAME CHARACTERISTICS ⁽²⁾			

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PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
UL Yellow Card Link	<u>E45329-101282614</u>	-	-
UL Recognized, 94V-0 Flame Class Rating	0.75	mm	UL 94
INJECTION MOLDING ⁽³⁾			
Extended Drying Temperature	150	°C	
Drying Time	4 – 6	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	360 – 400	°C	
Rear - Zone 1 Temperature	360 – 380	°C	
Middle - Zone 2 Temperature	370 – 390	°C	
Front - Zone 3 Temperature	380 – 400	°C	
Nozzle Temperature	390 – 400	°C	
Mold Temperature	140 – 180	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw speed (Circumferential speed)	0.2 – 0.3	m/s	
Vent Depth	0.025 – 0.076	mm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.

(3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

MORE INFORMATION

For curve data and CAE cards, please visit and register at <https://materialfinder.sabic-specialties.com>

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